Intel - 5SGXMA7H3F35C2 Datasheet





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Details

Product Status	Obsolete
Number of LABs/CLBs	234720
Number of Logic Elements/Cells	622000
Total RAM Bits	51200000
Number of I/O	552
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxma7h3f35c2

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Table 5 lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime. The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle. For example, a signal that overshoots to 3.95 V can be at 3.95 V for only ~21% over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~2 years.

Symbol	Description	Condition (V)	Overshoot Duration as % @ T _J = 100°C	Unit				
		3.8	100	%				
		3.85	64	%				
		3.9	36	%				
		3.95	21	%				
Vi (AC)	AC input voltage	4	12	%				
		4.05	7	%				
		4.1	4	%				
		4.15	2	%				
		4.2	1	%				

Table 5. Maximum Allowed Overshoot During Transitions

Figure 1. Stratix V Device Overshoot Duration



This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	_	0.87	0.9	0.93	V
V _{CC}	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) ⁽³⁾	_	0.82	0.85	0.88	V
V _{CCPT}	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
VI (1)	I/O pre-driver (3.0 V) power supply	_	2.85	3.0	3.15	V
V _{CCPD} ⁽¹⁾	I/O pre-driver (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply		2.85	3.0	3.15	V
	I/O buffers (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply		1.71	1.8	1.89	V
V _{CCIO}	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply	_	1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply	_	1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply	_	2.85	3.0	3.15	V
V _{CCPGM}	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V _{CCA_FPLL}	PLL analog voltage regulator power supply	_	2.375	2.5	2.625	V
V _{CCD_FPLL}	PLL digital voltage regulator power supply	_	1.45	1.5	1.55	V
V _{CCBAT} (2)	Battery back-up power supply (For design security volatile key register)	_	1.2	_	3.0	V
VI	DC input voltage	_	-0.5	_	3.6	V
V ₀	Output voltage	—	0	—	V _{CCIO}	V
т	Operating junction temperature	Commercial	0	—	85	°C
TJ	Operating junction temperature	Industrial	-40	_	100	°C

			Calibration Accuracy				
Symbol	Description	Conditions	C1	C2,12	C3,I3, I3YY	C4,14	Unit
50-Ω R _S	Internal series termination with calibration (50- Ω setting)	V _{CCI0} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%
34-Ω and 40-Ω R _S	Internal series termination with calibration (34- Ω and 40- Ω setting)	V _{CCI0} = 1.5, 1.35, 1.25, 1.2 V	±15	±15	±15	±15	%
48-Ω, 60-Ω, 80-Ω, and 240-Ω R _S	Internal series termination with calibration (48- Ω , 60- Ω , 80- Ω , and 240- Ω setting)	V _{CCI0} = 1.2 V	±15	±15	±15	±15	%
50-Ω R _T	Internal parallel termination with calibration (50-Ω setting)	V _{CCIO} = 2.5, 1.8, 1.5, 1.2 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
20- $Ω$, 30- $Ω$, 40- $Ω$,60- $Ω$, and 120- $Ω$ R _T	Internal parallel termination with calibration ($20 \cdot \Omega$, $30 \cdot \Omega$, $40 \cdot \Omega$, $60 \cdot \Omega$, and $120 \cdot \Omega$ setting)	V _{CCI0} = 1.5, 1.35, 1.25 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
60-Ω and 120-Ω R_T	Internal parallel termination with calibration (60- Ω and 120- Ω setting)	V _{CCI0} = 1.2	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
$\begin{array}{l} \textbf{25-}\Omega\\ \textbf{R}_{S_left_shift} \end{array}$	Internal left shift series termination with calibration (25- Ω R _{S_left_shift} setting)	V _{CCI0} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

Table 11. OCT Calibration Accurat	y Specifications for Stratix V Devices ⁽¹⁾ ((Part 2 of 2)
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Note to Table 11:

(1) OCT calibration accuracy is valid at the time of calibration only.

Table 12 lists the Stratix V OCT without calibration resistance to PVT changes.

			Resistance Tolerance				
Symbol	Description	Conditions	C1	C2,I2	C3, I3, I3YY	C4, I4	Unit
25-Ω R, 50-Ω R _S	Internal series termination without calibration (25- Ω setting)	$V_{CCIO} = 3.0$ and 2.5 V	±30	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25-Ω setting)	$V_{CCI0} = 1.8$ and 1.5 V	±30	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25-Ω setting)	V _{CCI0} = 1.2 V	±35	±35	±50	±50	%

Symbol	Description	V _{CCIO} (V)	Typical	Unit
dR/dT		3.0	0.189	
		2.5	0.208	
	OCT variation with temperature without recalibration	1.8	0.266	%/°C
	without robalibration	1.5	0.273	
		1.2	0.317	

Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2)⁽¹⁾

Note to Table 13:

(1) Valid for a V_{CCIO} range of $\pm 5\%$ and a temperature range of 0° to 85°C.

Pin Capacitance

Table 14 lists the Stratix V device family pin capacitance.

Table 14. Pin Capacitance for Stratix V Devices

Symbol	Description	Value	Unit
C _{IOTB}	Input capacitance on the top and bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on the left and right I/O pins	6	pF
C _{OUTFB}	Input capacitance on dual-purpose clock output and feedback pins	6	рF

Hot Socketing

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15.	Hot Socketing Specifications for Stratix V Devices
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Symbol	Description	Maximum
I _{IOPIN (DC)}	DC current per I/O pin	300 μA
I _{IOPIN (AC)}	AC current per I/O pin	8 mA ⁽¹⁾
I _{XCVR-TX (DC)}	DC current per transceiver transmitter pin	100 mA
I _{XCVR-RX (DC)}	DC current per transceiver receiver pin	50 mA

Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{10PIN}| = C dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.

I/O Standard	V _{IL(DI}	_{c)} (V)	V _{IH(D}	_{C)} (V)	V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{ol} (V)	V _{oh} (V)	I (mA)	I _{oh}
i/U Stanuaru	Min	Max	Min	Max	Max	Min	Max	Min	l _{oi} (mA)	(mA)
HSTL-18 Class I	_	V _{REF} – 0.1	V _{REF} + 0.1	_	$V_{REF} - 0.2$	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	8	-8
HSTL-18 Class II	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	16	-16
HSTL-15 Class I	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	8	-8
HSTL-15 Class II	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	16	-16
HSTL-12 Class I	-0.15	V _{REF} – 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} – 0.15	V _{REF} + 0.15	0.25* V _{CCI0}	0.75* V _{CCI0}	8	-8
HSTL-12 Class II	-0.15	V _{REF} – 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} – 0.15	V _{REF} + 0.15	0.25* V _{CCIO}	0.75* V _{CCI0}	16	-16
HSUL-12	_	V _{REF} – 0.13	V _{REF} + 0.13	_	V _{REF} – 0.22	V _{REF} + 0.22	0.1* V _{CCIO}	0.9* V _{CCI0}	_	_

Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 2 of 2)

Table 20. Differential SSTL I/O Standards for Stratix V Devices

I/O Standard		V _{ccio} (V)		V _{SWIN}	_{G(DC)} (V)		V _{X(AC)} (V)		V _{swing(} ,	_{AC)} (V)
ijo Stanuaru	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	V _{CCI0} + 0.6	V _{CCI0} /2- 0.2	_	V _{CCI0} /2 + 0.2	0.62	V _{CCI0} + 0.6
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	V _{CCI0} + 0.6	V _{CCI0} /2- 0.175	_	V _{CCI0} /2 + 0.175	0.5	V _{CCI0} + 0.6
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	(1)	V _{CCI0} /2- 0.15	_	V _{CCI0} /2 + 0.15	0.35	_
SSTL-135 Class I, II	1.283	1.35	1.45	0.2	(1)	V _{CCI0} /2- 0.15	V _{CCI0} /2	V _{CCI0} /2 + 0.15	2(V _{IH(AC)} - V _{REF})	2(V _{IL(AC)} - V _{REF})
SSTL-125 Class I, II	1.19	1.25	1.31	0.18	(1)	V _{CCI0} /2- 0.15	V _{CCI0} /2	V _{CCI0} /2 + 0.15	2(V _{IH(AC)} - V _{REF})	_
SSTL-12 Class I, II	1.14	1.2	1.26	0.18	_	V _{REF} -0.15	V _{CCI0} /2	V _{REF} + 0.15	-0.30	0.30

Note to Table 20:

(1) The maximum value for $V_{SWING(DC)}$ is not defined. However, each single-ended signal needs to be within the respective single-ended limits $(V_{IH(DC)} \text{ and } V_{IL(DC)})$.

I/O V _{CCI0} (V)			V _{DIF(DC)} (V)		V _{X(AC)} (V)			V _{CM(DC)} (V)			V _{DIF(AC)} (V)		
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	_	0.78	_	1.12	0.78	_	1.12	0.4	_
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	_	0.68	_	0.9	0.68	_	0.9	0.4	_

I/O		V _{ccio} (V)		V _{DIF(}	$V_{DIF(DC)}(V)$ $V_{X(AC)}(V)$			V _{CM(DC)} (V)	V _{DIF(AC)} (V)			
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V _{CCI0} + 0.3	_	0.5* V _{CCI0}	_	0.4* V _{CCI0}	0.5* V _{CCIO}	0.6* V _{CCIO}	0.3	V _{CCI0} + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5*V _{CCI0} - 0.12	0.5* V _{CCIO}	0.5*V _{CCI0} + 0.12	0.4* V _{CCIO}	0.5* V _{CCIO}	0.6* V _{CCIO}	0.44	0.44

Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 2 of 2)

Table 22. Differential I/O Standard Specifications for Stratix V Devices (7)

I/O	Vc	_{cio} (V)	(10)		V _{ID} (mV) ⁽⁸⁾			V _{ICM(DC)} (V)		Vo	_D (V) (5)	V	_{осм} (V) ((6)
Standard	Min	Тур	Max	Min	Condition	Max	Min	Condition	Max	Min	Тур	Max	Min	Тур	Max
PCML Transmitter, receiver, and input reference clock pins of the high-speed transceivers use the PCML I/O standard. transmitter, receiver, and reference clock I/O pin specifications, refer to Table 23 on page 18.						For									
2.5 V	2.375	2.5	2.625	100	V _{CM} =	_	0.05	D _{MAX} ≤ 700 Mbps	1.8	0.247	_	0.6	1.125	1.25	1.375
LVDS ⁽¹⁾	2.375	2.0	2.025	100	1.25 V	_	1.05	D _{MAX} > 700 Mbps	1.55	0.247	_	0.6	1.125	1.25	1.375
BLVDS (5)	2.375	2.5	2.625	100	_	_		—	_	_	_		_		
RSDS (HIO) ⁽²⁾	2.375	2.5	2.625	100	V _{CM} = 1.25 V	_	0.3	—	1.4	0.1	0.2	0.6	0.5	1.2	1.4
Mini- LVDS (HIO) ⁽³⁾	2.375	2.5	2.625	200		600	0.4	_	1.325	0.25	_	0.6	1	1.2	1.4
LVPECL (4			_	300		_	0.6	D _{MAX} ≤ 700 Mbps	1.8		_	_			
), (9)		_		300	_	_	1	D _{MAX} > 700 Mbps	1.6		_	_			—

Notes to Table 22:

(1) For optimized LVDS receiver performance, the receiver voltage input range must be between 1.0 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.

(2) For optimized RSDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.45 V.

(3) For optimized Mini-LVDS receiver performance, the receiver voltage input range must be between 0.3 V to 1.425 V.

- (4) For optimized LVPECL receiver performance, the receiver voltage input range must be between 0.85 V to 1.75 V for data rate above 700 Mbps and 0.45 V to 1.95 V for data rate below 700 Mbps.
- (5) There are no fixed V_{ICM} , V_{OD} , and V_{OCM} specifications for BLVDS. They depend on the system topology.
- (6) RL range: $90 \le RL \le 110 \Omega$.
- (7) The 1.4-V and 1.5-V PCML transceiver I/O standard specifications are described in "Transceiver Performance Specifications" on page 18.
- (8) The minimum VID value is applicable over the entire common mode range, VCM.
- (9) LVPECL is only supported on dedicated clock input pins.
- (10) Differential inputs are powered by VCCPD which requires 2.5 V.

Power Consumption

Altera offers two ways to estimate power consumption for a design—the Excel-based Early Power Estimator and the Quartus[®] II PowerPlay Power Analyzer feature.

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	nsceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Spread-spectrum downspread	PCle	_	0 to 0.5	_	_	0 to 0.5		_	0 to 0.5	_	%
On-chip termination resistors ⁽²¹⁾	_	_	100		_	100		_	100		Ω
Absolute V _{MAX} ⁽⁵⁾	Dedicated reference clock pin	_	_	1.6	_	_	1.6	_	_	1.6	V
	RX reference clock pin	_	_	1.2	_		1.2		_	1.2	
Absolute V_{MIN}	—	-0.4	—		-0.4	—	—	-0.4	—	—	V
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	200	_	1600	mV
V _{ICM} (AC	Dedicated reference 1050/1 clock pin		1050/1000/900/850 ⁽²⁾		1050/1000/900/850 ⁽²⁾			1050/	1000/90	00/850 ⁽²⁾	mV
coupled) ⁽³⁾	RX reference clock pin	1.	.0/0.9/0	.85 ⁽⁴⁾	1.	0/0.9/0	.85 ⁽⁴⁾	1.	0/0.9/0	.85 ⁽⁴⁾	V
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250		550	250		550	250		550	mV
	100 Hz	—	—	-70	—	—	-70	—	—	-70	dBc/Hz
Transmitter	1 kHz			-90			-90		—	-90	dBc/Hz
REFCLK Phase Noise	10 kHz	—	—	-100	—	—	-100	—	—	-100	dBc/Hz
(622 MHz) ⁽²⁰⁾	100 kHz			-110	—	—	-110	—	—	-110	dBc/Hz
	≥1 MHz	—	—	-120	—	—	-120	—	—	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁷⁾	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	_	_	3	ps (rms)
R _{REF} (19)			1800 ±1%		_	1800 ±1%	_		180 0 ±1%		Ω
Transceiver Clocks	S										
fixedclk clock frequency	PCIe Receiver Detect		100 or 125	_	_	100 or 125	_	_	100 or 125	_	MHz

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 2 of 7)

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 2 of 5)⁽¹⁾

Symbol/	Conditions		Transceive Speed Grade			Fransceive Deed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	Ī
	100 Hz			-70			-70	
Transmitter REFCLK	1 kHz		_	-90	_	_	-90	-
Phase Noise (622	10 kHz		_	-100	_	_	-100	dBc/Hz
MHz) ⁽¹⁸⁾	100 kHz		—	-110	_	—	-110	-
	\geq 1 MHz		—	-120	_	—	-120	-
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁵⁾	10 kHz to 1.5 MHz (PCIe)		_	3	_		3	ps (rms)
RREF ⁽¹⁷⁾	—		1800 ± 1%	_	_	1800 ± 1%	_	Ω
Transceiver Clocks								
fixedclk clock frequency	PCIe Receiver Detect		100 or 125	_	_	100 or 125	_	MHz
Reconfiguration clock (mgmt_clk_clk) frequency	_	100	_	125	100	_	125	MHz
Receiver				•				
Supported I/O Standards	—		1.4-V PCMI	_, 1.5-V PCM	L, 2.5-V PCI	ML, LVPEC	L, and LVDS	3
Data rate (Standard PCS) ⁽²¹⁾	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS) ⁽²¹⁾	GX channels	600	_	12,500	600	_	12,500	Mbps
Data rate	GT channels	19,600	—	28,050	19,600	—	25,780	Mbps
Absolute V _{MAX} for a receiver pin ⁽³⁾	GT channels	_	_	1.2	_	_	1.2	V
Absolute V _{MIN} for a receiver pin	GT channels	-0.4	_	_	-0.4		_	V
Maximum peak-to-peak	GT channels	_	—	1.6	—	—	1.6	V
differential input voltage V _{ID} (diff p-p) before device configuration ⁽²⁰⁾	GX channels				(8)			
	GT channels							
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p) after device configuration (¹⁶), (²⁰)	V _{CCR_GTB} = 1.05 V (V _{ICM} = 0.65 V)	—	-	2.2	_	_	2.2	V
oomguration (), ()	GX channels		•	•	(8)			
Minimum differential	GT channels	200	_		200			mV
eye opening at receiver serial input pins ⁽⁴⁾ , ⁽²⁰⁾	GX channels				(8)			

Symbol/	Conditions	5	Transceiver Speed Grade			Transceive peed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Differential on-chip termination resistors ⁽⁷⁾	GT channels		100	_	_	100	_	Ω
	85- Ω setting	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on-chip termination resistors	100-Ω setting	_	100 ± 30%	_	_	100 ± 30%	_	Ω
for GX channels ⁽¹⁹⁾	120-Ω setting	_	120 ± 30%	_	_	120 ± 30%	_	Ω
	150-Ω setting		150 ± 30%	_	_	150 ± 30%	_	Ω
V _{ICM} (AC coupled)	GT channels		650		—	650	—	mV
	VCCR_GXB = 0.85 V or 0.9 V		600	_	_	600		mV
VICM (AC and DC coupled) for GX Channels	VCCR_GXB = 1.0 V full bandwidth		700	_	_	700	_	mV
	VCCR_GXB = 1.0 V half bandwidth		750	_	_	750	_	mV
t _{LTR} ⁽⁹⁾	—	—	—	10	—	—	10	μs
t _{LTD} ⁽¹⁰⁾		4			4			μs
t _{LTD_manual} ⁽¹¹⁾	—	4	—	—	4	—	_	μs
t _{LTR_LTD_manual} ⁽¹²⁾	_	15			15	—		μs
Run Length	GT channels	_	—	72	—	—	72	CID
nun Lengin	GX channels				(8)			
CDR PPM	GT channels			1000	_	—	1000	± PPM
	GX channels				(8)			
Programmable	GT channels	_	_	14	—	—	14	dB
equalization (AC Gain) ⁽⁵⁾	GX channels				(8)			
Programmable	GT channels	_	—	7.5	—	—	7.5	dB
DC gain ⁽⁶⁾	GX channels				(8)			
Differential on-chip termination resistors ⁽⁷⁾	GT channels	_	100	_	_	100	_	Ω
Transmitter	·1					•		
Supported I/O Standards	_			1.4-V	and 1.5-V F	PCML		
Data rate (Standard PCS)	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS)	GX channels	600		12,500	600	_	12,500	Mbps

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 3 of 5)⁽¹⁾

Table 29 shows the V_{OD} settings for the GT channel.

Table 29.	Typical Von Setting	g for GT Channel, 1	EX Termination = 100 Ω
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Symbol	V _{OD} Setting	V _{op} Value (mV)
	0	0
	1	200
\mathbf{V}_{0D} differential peak to peak typical (1)	2	400
VOD unicicilitat peak to peak typical (*)	3	600
	4	800
	5	1000

Note:

(1) Refer to Figure 4.

Symbol	Parameter	Min	Тур	Max	Unit
+ (3) (4)	Input clock cycle-to-cycle jitter ($f_{REF} \ge 100 \text{ MHz}$)	_	—	0.15	UI (p-p)
t _{INCCJ} ^{(3),} ⁽⁴⁾	Input clock cycle-to-cycle jitter (f _{REF} < 100 MHz)	-750	_	+750	ps (p-p)
t	Period Jitter for dedicated clock output (f_{OUT} \geq 100 MHz)	_	_	175 ⁽¹⁾	ps (p-p)
t _{outpj_dc} ⁽⁵⁾	Period Jitter for dedicated clock output (f _{OUT} < 100 MHz)	_		17.5 ⁽¹⁾	mUI (p-p)
+ (5)	Period Jitter for dedicated clock output in fractional PLL ($f_{0UT} \geq 100 \mbox{ MHz})$	_	_	250 ⁽¹¹⁾ , 175 ⁽¹²⁾	ps (p-p)
t _{foutpj_dc} ⁽⁵⁾	Period Jitter for dedicated clock output in fractional PLL (f _{OUT} < 100 MHz)	_	_	25 ⁽¹¹⁾ , 17.5 ⁽¹²⁾	mUI (p-p)
+	Cycle-to-Cycle Jitter for a dedicated clock output ($f_{OUT} \ge 100 \text{ MHz}$)	_	_	175	ps (p-p)
t _{outccj_dc} ⁽⁵⁾	Cycle-to-Cycle Jitter for a dedicated clock output (f _{0UT} < 100 MHz)	_	_	17.5	mUI (p-p)
+ <i>(5)</i>	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL (f_{OUT} \geq 100 MHz)	_	_	250 ⁽¹¹⁾ , 175 ⁽¹²⁾	ps (p-p)
t _{FOUTCCJ_DC} ⁽⁵⁾	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ($f_{OUT} < 100 \text{ MHz}$)+	_	_	25 ⁽¹¹⁾ , 17.5 ⁽¹²⁾	mUI (p-p)
t _{outpj_io} (5),	Period Jitter for a clock output on a regular I/O in integer PLL (f_{OUT} \geq 100 MHz)	_	_	600	ps (p-p)
OUTPJ_IO (***) (8)	Period Jitter for a clock output on a regular I/O (f _{OUT} < 100 MHz)	_	_	60	mUI (p-p)
t _{FOUTPJ_IO} (5),	Period Jitter for a clock output on a regular I/O in fractional PLL ($f_{OUT} \ge 100 \text{ MHz}$)	_	_	600 (10)	ps (p-p)
(8), (11)	Period Jitter for a clock output on a regular I/O in fractional PLL (f _{OUT} < 100 MHz)	_	_	60 ⁽¹⁰⁾	mUI (p-p)
t _{outccj_io} (5),	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL (f_{OUT} \geq 100 MHz)	_	_	600	ps (p-p)
(8)	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL (f_{OUT} < 100 MHz)	_	_	60 ⁽¹⁰⁾	mUI (p-p)
t _{foutccj_10} ^{(5),}	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ($f_{0UT} \geq 100 \mbox{ MHz})$	_	_	600 ⁽¹⁰⁾	ps (p-p)
(8), (11)	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ($f_{OUT} < 100 \text{ MHz}$)	_	_	60	mUI (p-p)
t _{casc_outpj_dc}	Period Jitter for a dedicated clock output in cascaded PLLs (f_{0UT} \geq 100 MHz)		_	175	ps (p-p)
(5), (6)	Period Jitter for a dedicated clock output in cascaded PLLs (f _{OUT} < 100 MHz)		_	17.5	mUI (p-p)
f _{DRIFT}	Frequency drift after PFDENA is disabled for a duration of 100 μs	_	_	±10	%
dK _{BIT}	Bit number of Delta Sigma Modulator (DSM)	8	24	32	Bits
k _{value}	Numerator of Fraction	128	8388608	2147483648	

Table 31. PLL Specifications for Stratix V Devices (Part 2 of 3)

Table 31. PLL Specifications for Stratix V Devices (Part 3 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
f _{RES}	Resolution of VCO frequency ($f_{INPFD} = 100 \text{ MHz}$)	390625	5.96	0.023	Hz

Notes to Table 31:

(1) This specification is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.

(2) This specification is limited by the lower of the two: I/O f_{MAX} or f_{OUT} of the PLL.

- (3) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source < 120 ps.
- (4) f_{REF} is fIN/N when N = 1.
- (5) Peak-to-peak jitter with a probability level of 10⁻¹² (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in Table 44 on page 52.
- (6) The cascaded PLL specification is only applicable with the following condition: a. Upstream PLL: 0.59Mhz ≤ Upstream PLL BW < 1 MHz b. Downstream PLL: Downstream PLL BW > 2 MHz
- (7) High bandwidth PLL settings are not supported in external feedback mode.
- (8) The external memory interface clock output jitter specifications use a different measurement method, which is available in Table 42 on page 50.
- (9) The VCO frequency reported by the Quartus II software in the PLL Usage Summary section of the compilation report takes into consideration the VCO post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the f_{VCO} specification.
- (10) This specification only covers fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.05 0.95 must be \geq 1000 MHz, while f_{VCO} for fractional value range 0.20 0.80 must be \geq 1200 MHz.
- (11) This specification only covered fractional PLL for low bandwidth. The f_{VC0} for fractional value range 0.05-0.95 must be \geq 1000 MHz.
- (12) This specification only covered fractional PLL for low bandwidth. The f_{VC0} for fractional value range 0.20-0.80 must be \geq 1200 MHz.

DSP Block Specifications

Table 32 lists the Stratix V DSP block performance specifications.

	Peformance							
Mode	C1	C2, C2L	12, 12L	C3	13, 13L, 13YY	C4	14	Unit
		Modes ι	ising one	DSP				4
Three 9 x 9	600	600	600	480	480	420	420	MHz
One 18 x 18	600	600	600	480	480	420	400	MHz
Two partial 18 x 18 (or 16 x 16)	600	600	600	480	480	420	400	MHz
One 27 x 27	500	500	500	400	400	350	350	MHz
One 36 x 18	500	500	500	400	400	350	350	MHz
One sum of two 18 x 18(One sum of 2 16 x 16)	500	500	500	400	400	350	350	MHz
One sum of square	500	500	500	400	400	350	350	MHz
One 18 x 18 plus 36 (a x b) + c	500	500	500	400	400	350	350	MHz
		Modes u	sing two l	DSPs	1		•	1
Three 18 x 18	500	500	500	400	400	350	350	MHz
One sum of four 18 x 18	475	475	475	380	380	300	300	MHz
One sum of two 27 x 27	465	465	450	380	380	300	290	MHz
One sum of two 36 x 18	475	475	475	380	380	300	300	MHz
One complex 18 x 18	500	500	500	400	400	350	350	MHz
One 36 x 36	475	475	475	380	380	300	300	MHz

Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 1 of 2)

Periphery Performance

This section describes periphery performance, including high-speed I/O and external memory interface.

I/O performance supports several system interfaces, such as the **LVDS** high-speed I/O interface, external memory interface, and the **PCI/PCI-X** bus interface. General-purpose I/O standards such as 3.3-, 2.5-, 1.8-, and 1.5-**LVTTL/LVCMOS** are capable of a typical 167 MHz and 1.2-**LVCMOS** at 100 MHz interfacing frequency with a 10 pF load.

The actual achievable frequency depends on design- and system-specific factors. Ensure proper timing closure in your design and perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

High-Speed I/O Specification

Table 36 lists high-speed I/O timing for Stratix V devices.

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 1 of 4)

Sumbol	Conditiono		C1		C2,	C2L, I	2, I2L	C3,	13, 13L	., I 3YY		C4,I	4	Ilmit
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{HSCLK_in} (input clock frequency) True Differential I/O Standards	Clock boost factor W = 1 to 40 $^{(4)}$	5		800	5		800	5		625	5		525	MHz
f _{HSCLK_in} (input clock frequency) Single Ended I/O Standards ⁽³⁾	Clock boost factor W = 1 to 40 $^{(4)}$	5		800	5	_	800	5		625	5		525	MHz
f _{HSCLK_in} (input clock frequency) Single Ended I/O Standards	Clock boost factor W = 1 to 40 $^{(4)}$	5		520	5		520	5		420	5		420	MHz
f _{HSCLK_OUT} (output clock frequency)	_	5	_	800	5	_	800	5	_	625 (5)	5	_	525 (5)	MHz

Symbol	Description	Min	Max	Unit
t _{JPH}	JTAG port hold time	5	—	ns
t _{JPCO}	JTAG port clock to output	—	11 ⁽¹⁾	ns
t _{JPZX}	JTAG port high impedance to valid output	—	14 ⁽¹⁾	ns
t _{JPXZ}	JTAG port valid output to high impedance	—	1 4 ⁽¹⁾	ns

Table 46. JTAG Timing Parameters and Values for Stratix V Devices

Notes to Table 46:

(1) A 1 ns adder is required for each V_{CCI0} voltage step down from 3.0 V. For example, $t_{JPC0} = 12$ ns if V_{CCI0} of the TDO I/O bank = 2.5 V, or 13 ns if it equals 1.8 V.

(2) The minimum TCK clock period is 167 ns if VCCBAT is within the range 1.2V-1.5V when you perform the volatile key programming.

Raw Binary File Size

For the POR delay specification, refer to the "POR Delay Specification" section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices".

Table 47 lists the uncompressed raw binary file (.rbf) sizes for Stratix V devices.

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) ^{(4), (5)}
	ECCVA0	H35, F40, F35 ⁽²⁾	213,798,880	562,392
	5SGXA3	H29, F35 ⁽³⁾	137,598,880	564,504
	5SGXA4	_	213,798,880	563,672
	5SGXA5	_	269,979,008	562,392
	5SGXA7	_	269,979,008	562,392
Stratix V GX	5SGXA9	_	342,742,976	700,888
	5SGXAB	_	342,742,976	700,888
	5SGXB5	_	270,528,640	584,344
	5SGXB6	_	270,528,640	584,344
	5SGXB9	_	342,742,976	700,888
	5SGXBB	_	342,742,976	700,888
Stratix V GT	5SGTC5	_	269,979,008	562,392
	5SGTC7	—	269,979,008	562,392
	5SGSD3	_	137,598,880	564,504
	5SGSD4	F1517	213,798,880	563,672
Ctratic V CC	556504	_	137,598,880	564,504
Stratix V GS	5SGSD5	_	213,798,880	563,672
	5SGSD6	_	293,441,888	565,528
	5SGSD8	_	293,441,888	565,528

Table 47. Uncompressed .rbf Sizes for Stratix V Devices

	Member		Active Serial (1))	Fas	t Passive Parall	assive Parallel ⁽²⁾	
Variant	Code	Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)	
	D3	4	100	0.344	32	100	0.043	
	D4	4	100	0.534	32	100	0.067	
GS	D4	4	100	0.344	32	100	0.043	
65	D5	4	100	0.534	32	100	0.067	
	D6	4	100	0.741	32	100	0.093	
	D8	4	100	0.741	32	100	0.093	
Е	E9	4	100	0.857	32	100	0.107	
	EB	4	100	0.857	32	100	0.107	

Table 48. Minimum Configuration Time Estimation for Stratix V Devices

Notes to Table 48:

(1) DCLK frequency of 100 MHz using external CLKUSR.

(2) Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

Fast Passive Parallel Configuration Timing

This section describes the fast passive parallel (FPP) configuration timing parameters for Stratix V devices.

DCLK-to-DATA[] Ratio for FPP Configuration

FPP configuration requires a different DCLK-to-DATA[]ratio when you enable the design security, decompression, or both features. Table 49 lists the DCLK-to-DATA[]ratio for each combination.

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×8	Disabled	Enabled	1
FFF X0	Enabled	Disabled	2
	Enabled	Enabled	2
	Disabled	Disabled	1
FPP ×16	Disabled	Enabled	2
	Enabled	Disabled	4
	Enabled	Enabled	4

 Table 49. DCLK-to-DATA[] Ratio ⁽¹⁾ (Part 1 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×32	Disabled	Enabled	4
FFF X02	Enabled	Disabled	8
	Enabled	Enabled	8

Note to Table 49:

(1) Depending on the DCLK-to-DATA [] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA [] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

Figure 11. Single Device FPP Configuration Using an External Host



Notes to Figure 11:

- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device. V_{CCPGM} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with V_{CCPGM} .
- (2) You can leave the nCEO pin unconnected or use it as a user I/O pin when it does not feed another device's nCE pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP ×8, use DATA [7..0]. If you use FPP ×16, use DATA [15..0].

IF the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio – 1) clock cycles after the last data is latched into the Stratix V device.

Table 50 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA[] ratio is 1.

Table 50. FPP Timing Parameters for Stratix V Devices (1)

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t _{CFG}	nCONFIG low pulse width	2	—	μS
t _{status}	nSTATUS low pulse width	268	1,506 ⁽²⁾	μS
t _{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 ⁽³⁾	μS
t _{CF2CK} (6)	nCONFIG high to first rising edge on DCLK	1,506	_	μS
t _{ST2CK} ⁽⁶⁾	nSTATUS high to first rising edge of DCLK	2	_	μS
t _{DSU}	DATA [] setup time before rising edge on DCLK	5.5	_	ns
t _{DH}	DATA [] hold time after rising edge on DCLK	0	_	ns
t _{CH}	DCLK high time	$0.45\times1/f_{MAX}$	—	S
t _{CL}	DCLK low time	$0.45\times1/f_{MAX}$	—	S
t _{CLK}	DCLK period	1/f _{MAX}	_	S
f	DCLK frequency (FPP ×8/×16)	—	125	MHz
f _{MAX}	DCLK frequency (FPP ×32)	—	100	MHz
t _{CD2UM}	CONF_DONE high to user mode ⁽⁴⁾	175	437	μS
+	CONTRACT high to an union analysis	4 × maximum		
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	DCLK period	—	
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$\begin{array}{c} t_{\text{CD2CU}} + \\ (8576 \times \text{CLKUSR} \\ \text{period}) \ ^{(5)} \end{array}$	_	_

Notes to Table 50:

(1) Use these timing parameters when the decompression and design security features are disabled.

(2) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

(3) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.

- (4) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.
- (5) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (6) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

FPP Configuration Timing when DCLK-to-DATA [] > 1

Figure 13 shows the timing waveform for FPP configuration when using a MAX II device, MAX V device, or microprocessor as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is more than 1.

Symbol	Parameter	Minimum	Maximum	Units
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	—
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{cd2cu} + (8576 × clkusr period)	_	—

Table 53. AS Timing Parameters for AS \times 1 and AS \times 4 Configurations in Stratix V Devices ^{(1), (2)} (Part 2 of 2)

Notes to Table 53:

(1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.

(2) t_{CF2CD}, t_{CF2ST0}, t_{CF2ST0}, t_{CF6}, t_{STATUS}, and t_{CF2ST1} timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63.

(3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform ⁽¹⁾



Notes to Figure 15:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds <code>nSTATUS</code> low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATAO is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

Remote System Upgrades

Table 56 lists the timing parameter specifications for the remote system upgrade circuitry.

Table 56. Remote System Upgrade Circuitry Timing Specifications	Table 56.	Remote System	Upgrade Circuitry	y Timing S	Specifications
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Parameter	Minimum	Maximum	Unit
t _{RU_nCONFIG} ⁽¹⁾	250	—	ns
t _{RU_nRSTIMER} ⁽²⁾	250	—	ns

Notes to Table 56:

- (1) This is equivalent to strobing the reconfiguration input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the Remote System Upgrade State Machine section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (2) This is equivalent to strobing the reset_timer input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the User Watchdog Timer section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

User Watchdog Internal Circuitry Timing Specification

Table 57 lists the operating range of the 12.5-MHz internal oscillator.

Table 57. 12.5-MHz Internal Oscillator Specifications

Minimum	Typical	Maximum	Units		
5.3	7.9	12.5	MHz		

I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O Timing and the Quartus II Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis. The Quartus II Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

 You can download the Excel-based I/O Timing spreadsheet from the Stratix V Devices Documentation web page.

Programmable IOE Delay

Table 58 lists the Stratix V IOE programmable delay settings.

Table 58. IOE Programmable Delay for Stratix V Devices (Part 1 of 2)

Parameter (1)	Available	Min	Fast Model		Slow Model							
	Available Settings	Offset (2)	Industrial	Commercial	C1	C2	C3 C4	12	13, 13YY	14	Unit	
D1	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D2	32	0	0.230	0.244	0.415	0.415	0.459	0.503	0.417	0.456	0.500	ns

Table 61. Document Revision History (Part 2 of 3)

Date	Version	Changes				
		Added the I3YY speed grade and changed the data rates for the GX channel in Table 1.				
	3.3	 Added the I3YY speed grade to the V_{CC} description in Table 6. 				
		 Added the I3YY speed grade to V_{CCHIP_L}, V_{CCHIP_R}, V_{CCHSSI_L}, and V_{CCHSSI_R} descriptions in Table 7. 				
		■ Added 240-Ω to Table 11.				
		Changed CDR PPM tolerance in Table 23.				
		 Added additional max data rate for fPLL in Table 23. 				
		 Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 25. 				
		 Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 26. 				
		Changed CDR PPM tolerance in Table 28.				
		 Added additional max data rate for fPLL in Table 28. 				
		Changed the mode descriptions for MLAB and M20K in Table 33.				
		■ Changed the Max value of f _{HSCLK_OUT} for the C2, C2L, I2, I2L speed grades in Table 36.				
November 2014		 Changed the frequency ranges for C1 and C2 in Table 39. 				
		Changed the .rbf file sizes for 5SGSD6 and 5SGSD8 in Table 47.				
		 Added note about nSTATUS to Table 50, Table 51, Table 54. 				
		 Changed the available settings in Table 58. 				
		 Changed the note in "Periphery Performance". 				
		 Updated the "I/O Standard Specifications" section. 				
		 Updated the "Raw Binary File Size" section. 				
		 Updated the receiver voltage input range in Table 22. 				
		 Updated the max frequency for the LVDS clock network in Table 36. 				
		■ Updated the DCLK note to Figure 11.				
		 Updated Table 23 VO_{CM} (DC Coupled) condition. 				
		 Updated Table 6 and Table 7. 				
		■ Added the DCLK specification to Table 55.				
		 Updated the notes for Table 47. 				
		 Updated the list of parameters for Table 56. 				
November 2013	3.2	Updated Table 28				
November 2013	3.1	Updated Table 33				
November 2013	3.0	Updated Table 23 and Table 28				
October 2013	2.9	 Updated the "Transceiver Characterization" section 				
	2.8	 Updated Table 3, Table 12, Table 14, Table 19, Table 20, Table 23, Table 24, Table 28, Table 30, Table 31, Table 32, Table 33, Table 36, Table 39, Table 40, Table 41, Table 42, Table 47, Table 53, Table 58, and Table 59 				
October 2013		 Added Figure 1 and Figure 3 				
		 Added the "Transceiver Characterization" section 				
		 Removed all "Preliminary" designations. 				